G593-ZD1-AAX3

HPC/AI Server - 5U DP NVIDIA HGX™ H200 8-GPU









Features

- NVIDIA HGX™ H200 8-GPU
- 900GB/s GPU-to-GPU bandwidth with NVLink® and NVSwitch™
- Dual AMD EPYC[™] 9005/9004 Series Processors
- 12-Channel RDIMM DDR5, 24 x DIMMs
- · Dual ROM Architecture
- 2 x 10Gb/s LAN ports via Intel® X710-AT2
- 2 x M.2 slots with PCle Gen3 x4 and x1 interface
- 8 x 2.5" Gen5 NVMe hot-swappable bays
- 4 x FHHL PCIe Gen5 x16 slots
- 8 x LP PCIe Gen5 x16 slots
- 6 x 3000W 80 PLUS Titanium redundant power supplies

Application

AI, AI Inference, AI Training, High-Performance Computing

Specification

Dimensions	5U (W447 x H219.7 x D945 mm)	RAID	Require RAID add-in cards
Motherboard	MZB3-G43	ТРМ	1 x TPM header with SPI interface (Optional TPM2.0 kit: CTM010)
CPU	AMD EPYC [™] 9005 Series Processors AMD EPYC [™] 9004 Series Processors Dual processor, Socket SP5, cTDP up to 400W - At ambient 25°C, cTDP up to 500W	Backplane Board	Speed and bandwidth: PCIe Gen5 x4 or SATA 6Gb/s or SAS-4 24Gb/s
		Power Supply	4+2 3000W 80 PLUS Titanium redundant power supply AC Input: 115-240V *The system power supply requires C19 power cord.
Chipset	System on Chip		
Memory	12-Channel DDR5 RDIMM, 24 x DIMMs [EPYC 9005] Up to 6000 MT/s	System Management	ASPEED® AST2600 management controller GIGABYTE Management Console (AMI MegaRAC SP-X)
LAN	[EPYC 9004] Up to 4800 MT/s 2 x 10Gb/s LAN ports (1 x Intel® X710-AT2) - Support NCSI function 1 x 10/100/1000 management LAN	OS Support	Windows Server, Red Hat Enterprise Linux server, Ubuntu, SUSE Linux Enterprise server, VMware ESXi, Citrix Hypervisor
LAN		System Fans	2 x 40x40x56mm (32,000rpm), 4 x 60x60x56mm (24,000rpm), 4 x 40x40x28mm (25,000rpm), 2 x 40x40x56mm (32,000rpm) 6 x 60x60x76mm (21,700rpm), 11 x 80x80x80mm (17,000rpm)
Video	Integrated in ASPEED® AST2600 - 1 x VGA port		
E * I 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	Front hot-swap: 8 x 2.5" Gen5 NVMe/SATA/SAS-4 *Storage card is required to support SATA and SAS drives. Internal M.2: 1 x M.2 (2280/22110), PCIe Gen3 x4 1 x M.2 (2280/22110), PCIe Gen3 x1	Operating Properties	Operating temperature: 10°C to 35°C Operating humidity: 8-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
		Packaging Content	1 x G593-ZD1-AAX3, 2 x CPU heatsinks, 1 x L-shape Rail kit
Modular GPU	NVIDIA HGX™ H200 with 8 x SXM GPUs		Packaging Dimensions: 1200 x 890 x 700 mm
Expansion Slots	8 x PCle Gen5 x16 low-profile slots 4 x PCle Gen5 x16 FHHL slots	Part Numbers	Barebone w/ NVIDIA module: 6NG593ZD1DR000ACX3* Optional parts: - C19 power cord 125V/15A (US): 25CP1-018000-Q0R - C19 power cord 250V/16A (EU): 25CP3-01830H-Q0R - C19 power cord 125V/15A (JP): 25CPA-01830B-Q0R
I/O ports	Front: 2 x USB 3.2 Gen1, 1 x VGA, 2 x RJ45, 1 x MLAN (default) Rear: 1 x MLAN		



Learn more at https://www.GIGABYTE.com/enterprise

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